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APPLICATION NO.	Fl	LING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/081,767	(02/25/2002	Shunpei Yamazaki	740756-2443	9406
22204	7590	07/05/2005		EXAMINER	
NIXON PEA			NGUYEN, THANH T		
401 9TH STREET, NW SUITE 900				ART UNIT	PAPER NUMBER
WASHINGTON, DC 20004-2128				2813	
				DATE MAILED: 07/05/2005	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
	10/081,767	YAMAZAKI ET AL.				
Office Action Summary	Examiner	Art Unit				
	Thanh T. Nguyen	2813				
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address				
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply if NO period for reply is specified above, the maximum statutory period was realized to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	6(a). In no event, however, may a reply be tim within the statutory minimum of thirty (30) days rill apply and will expire SIX (6) MONTHS from to cause the application to become ABANDONED	ely filed will be considered timely. the mailing date of this communication. 0 (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 17 Ju	ne 2005.					
2a) ☐ This action is FINAL . 2b) ☑ This	action is non-final.					
3) Since this application is in condition for allowance except for formal matters, prosecution as to the ments is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Disposition of Claims						
4) Claim(s) 6-8,17-22,25 and 49-85 is/are pending in the application. 4a) Of the above claim(s) is/are withdrawn from consideration. 5) Claim(s) is/are allowed. 6) Claim(s) 6-8,17-22,25 and 49-85 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or election requirement.						
Application Papers						
9) The specification is objected to by the Examiner.						
10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner.						
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.						
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the priorical application from the International Bureau * See the attached detailed Office action for a list of	s have been received. s have been received in Application ity documents have been receive n (PCT Rule 17.2(a)).	on No ed in this National Stage				
Attachment(s)						
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 4) Interview Summary (PTO-413) Paper No(s)/Mail Date						
3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date		atent Application (PTO-152)				

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DETAILED ACTION

Response to Arguments

Applicant's arguments, see page 1, filed 6/17/05, with respect to the rejection(s) of claim(s) 6-8, 17-22, 25 and 49-85 under 35 U.S.C. 102 and 103 have been fully considered and are persuasive. Therefore, the rejection has been withdrawn. However, upon further consideration, a new ground(s) of rejection is made in view of Yamazaki et al. (U.S. Patent No. 5,907,770).

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 6-7, 25, 49, 50, 54-55, 64, 66-67, 76, 78-81 are rejected under 35 U.S.C. 102(b) as being anticipated by Yamazaki et al. (U.S. Patent No. 5,907,770).

Referring to figures 1+, Yamazaki et al. teaches a method of manufacturing a semiconductor device, comprising the steps of:

Adding a metal element (Ni, see col. 12, lines 1-5, col. 14, lines 30-45, as claimed in

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claims 25, 64, 76, 81) to an amorphous semiconductor film (see col. 14, lines 30-45, , as claimed in claims 79, 83);

First heating the amorphous semiconductor film to form a first crystalline semiconductor film (see col. 12, lines 13-18),

Irradiating a semiconductor film (103) with a laser light to improve crystallinity of the semiconductor film wherein a warp is created in the semiconductor film due to the irradiating with the laser light (high power, see col. 5, lines 34-48, col. 24, lines 60-63).

Heating the semiconductor film in order to decrease the warp (low power, col. 24, lines 40-67)

Etching the semiconductor film (103) to form at lease one semiconductor island after the heating step (see col. 13, lines 25-65)

Regarding to claims 49, 54, 66, excimer laser (see col. 13, lines 1-6).

Regarding to claims 50, 67, the laser light has a rectangular or linear shape (see col. 13, lines 11-16). The shape of the light does not make the device function different therefore it would have been obvious to form the laser light has a rectangular or linear shape as a design choice.

Regarding to claims 79, 83, the semiconductor film is amorphous silicon (see col. 14, lines 30-45).

Regarding to claims 80, 84, semiconductor film is crystallized before irradiation with the laser light (see col. 12, lines 13-18).

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Regarding to claims 81, 85, the semiconductor film is crystallized before the irradiation with the laser light where the crystallization of the semiconductor film is promoted by adding a metal element thereto (Ni, see col. 12, lines 1-5, col. 14, lines 30-45).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 8, 17-22, 25 and 51-53, 56-63, 65, 68-75, 77, 82-85 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yamazaki et al. (U.S. Patent No. 5,907,770) as applied to claims 6-7, 25, 49-50, 54-55, 64, 66-67, 76, 78-81 above in view of Joo et al. (U.S. Patent No. 6,197,623).

Yamazaki et al. teaches a method of manufacturing a semiconductor device, comprising the steps of:

Adding a metal element (Ni, see col. 12, lines 1-5, col. 14, lines 30-45, as claimed in claims 25, 64, 76, 81) to an amorphous semiconductor film (see col. 14, lines 30-45, , as claimed in claims 79, 83);

First heating the amorphous semiconductor film to form a first crystalline semiconductor film (see col. 12, lines 13-18),

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Irradiating a semiconductor film (103) with a laser light to improve crystallinity of the semiconductor film wherein a warp is created in the semiconductor film due to the irradiating with the laser light (high power, see col. 5, lines 34-48, col. 24, lines 60-63).

Heating the semiconductor film in order to decrease the warp (low power, col. 24, lines 40-67)

Etching the semiconductor film (103) to form at lease one semiconductor island after the heating step (see col. 13, lines 25-65)

Regarding to claims 49, 54, 66, excimer laser (see col. 13, lines 1-6).

Regarding to claims 50, 67, the laser light has a rectangular or linear shape (see col. 13, lines 11-16). The shape of the light does not make the device function different therefore it would have been obvious to form the laser light has a rectangular or linear shape as a design choice.

Regarding to claims 79, 83, the semiconductor film is amorphous silicon (see col. 14, lines 30-45).

Regarding to claims 80, 84, semiconductor film is crystallized before irradiation with the laser light (see col. 12, lines 13-18).

Regarding to claims 81, 85, the semiconductor film is crystallized before the irradiation with the laser light where the crystallization of the semiconductor film is promoted by adding a metal element thereto (Ni, see col. 12, lines 1-5, col. 14, lines 30-45).

However, the reference does not teach etching the semiconductor film to form a semiconductor island before the heating to decrease warp, lamp light is radiated from halogen lamp radiated in the second heating step, lamp light is radiated from at least one selected form

the group consisting of an upper side and lower side of the substrate, form the amorphous layer by using the LPCVD, semiconductor device as claimed above to use as display or camera or computer or telephone, the specific temperature range, the time range, the rate of heating.

It is noted that absent a showing of unexpected result, a change in sequence involves routine optimization of process of prior art and would have been obvious to one skilled in the art at the time the invention was made. A change in sequence/reversal of process steps is obvious under 35 USC 103 (exparte Rubin, 128 USPQ 440 (Bd. App. 1959)). See also in re Burhans, 154 F.2d 690,69 USPQ 330 (CCPA).

Therefore, it would have been obvious to a person of ordinary skill in the requisite art at the time of the invention was made would etch the semiconductor film to form an semiconductor island before the heating to decrease warp in process of Yamazaki et al. because the process would form a TFT device.

Yamazaki et al. teaches thermal anneal the in nitrogen at the temperature of 450°C on the device (see figure 1F). However, Yamazaki et al. does not teach thermal anneal is halogen lamp.

Joo et al. teaches thermal annealing is annealing by using halogen lamp (see col. 4, lines 32-40). Joo et al. also teaches thermal annealing apparatus by using a furnace (see col. 2, lines 6-11).

Therefore, it would have been obvious to a person of ordinary skill in the requisite art at the time of the invention was made would using lamp light is radiated from halogen lamp radiated in the second heating step in process of Yamazaki in process of Joo et al. because the process would enhance a yield of large area LCD products (see col. 10, lines 10-18).

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It is known in the art to forming an amorphous layer by LPCVD process.

Therefore, it would have been obvious to a person of ordinary skill in the requisite art at the time of the invention was made would form an amorphous layer by LPCVD in process of Yamazaki because forming a layer by LPCVD process would form a conformal layer with good step coverage.

Regarding to claims 53, 55, 77, It is obvious to one of ordinary skill in the requisite art at the time of the invention was made to form a semiconductor device as claimed above to use as display or camera or computer or telephone.

The temperature range, the time range, the rate of heating are considered to involve routine optimization while has been held to be within the level of ordinary skill in the art. As noted in In re Aller 105 USPQ233, the selection of reaction parameters such as temperature and concentration would have been obvious:

"Normally, it is to be expected that a change in temperature, or in concentration, or in both, would be an unpatentable modification. Under some circumstances, however, changes such as these may impart patentability to a process if the particular ranges claimed produce a new and unexpected result which is different in kind and not merely degree from the results of the prior art...such ranges are termed "critical ranges and the applicant has the burden of proving such criticality.... More particularly, where the general conditions of a claim are disclosed in the prior art, it is not inventive to discover the optimum or workable ranges by routine experimentation."

In re Aller 105 USPQ233, 255 (CCPA 1955). See also In re Waite 77 USPQ 586 (CCPA 1948); In re Scherl 70 USPQ 204 (CCPA 1946); In re Irmscher 66 USPQ 314 (CCPA 1945); In re Norman 66 USPQ 308 (CCPA 1945); In re Swenson 56 USPQ 372 (CCPA 1942); In re Sola 25 USPQ 433 (CCPA 1935); In re Dreyfus 24 USPQ 52 (CCPA 1934).

Therefore, one of ordinary skill in the requisite art at the time the invention was made would have used any temperature range, the time range, the rate of heating range suitable to the method in process of Yamazaki et al. in order to optimize the process.

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Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thanh Nguyen whose telephone number is (571) 272-1695, or by Email via address Thanh Nguyen@uspto.gov. The examiner can normally be reached on Monday-Thursday from 6:00AM to 3:30PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead, can be reached on (571) 272-1702. The fax phone number for this Group is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the Group receptionist whose telephone number is (703) 308-0956 (See MPEP 203.08).

Thanh Nguyen
Patent Examiner

Patent Examining Group 2800

TTN